

Electronic Patent Application Fee Transmittal

Application Number:	10599638			
Filing Date:	04-Oct-2006			
Title of Invention:	Bonding method and apparatus			
First Named Inventor/Applicant Name:	Tatsuo Sasaoka			
Filer:	Linda Johnson Hodge/Son T. Nguyen			
Attorney Docket Number:	P30908			
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Basic Filing:				
Pages:				
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Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Submission- Information Disclosure Stmt	1806	1	180	180
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